

General Description

The HSL0115 uses advanced trench MOSFET technology to provide excellent $R_{DS(ON)}$ and gate charge for use in a wide variety of other applications.

The HSL0115 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

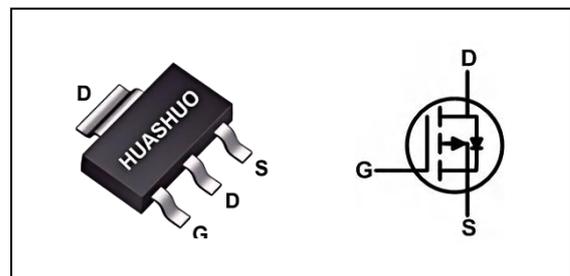
Features

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench Technology

Product Summary

| | | |
|------------------|------|------------|
| V_{DS} | -100 | V |
| $R_{DS(ON),typ}$ | 75 | m Ω |
| I_D | -5 | A |

SOT-223 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|----------------------|---|------------|------------|
| V_{DS} | Drain-Source Voltage | -100 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | V |
| $I_D@T_A=25^\circ C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -5 | A |
| $I_D@T_A=70^\circ C$ | Continuous Drain Current, $V_{GS} @ -10V^1$ | -4 | A |
| I_{DM} | Pulsed Drain Current ² | -20 | A |
| EAS | Single Pulse Avalanche Energy ³ | 90 | mJ |
| I_{AS} | Avalanche Current | 18.9 | A |
| $P_D@T_A=25^\circ C$ | Total Power Dissipation ⁴ | 2 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 65 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 25 | $^\circ C/W$ |



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|--|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =-250uA | -100 | --- | --- | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =-10V, I _D =-5A | --- | 75 | 95 | mΩ |
| | | V _{GS} =-4.5V, I _D =-3A | --- | 80 | 110 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =-250uA | -1.2 | -1.8 | -2.5 | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-100V, V _{GS} =0V, T _J =25°C | --- | --- | -1 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| gfs | Forward Transconductance | V _{DS} =-10V, I _D =-5A | --- | 24 | --- | S |
| Q _g | Total Gate Charge | V _{DS} =-50V, V _{GS} =-10V, I _D =-5A | --- | 44.5 | --- | nC |
| Q _{gs} | Gate-Source Charge | | --- | 9.13 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 5.93 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =-50V, V _{GS} =-10V, R _G =3.3Ω, I _D =-5A | --- | 12 | --- | ns |
| T _r | Rise Time | | --- | 27.4 | --- | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 79 | --- | |
| T _f | Fall Time | | --- | 53.6 | --- | |
| C _{iss} | Input Capacitance | V _{DS} =-20V, V _{GS} =0V, f=1MHz | --- | 3029 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 129 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 76 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I _S | Continuous Source Current ^{1,5} | V _G =V _D =0V, Force Current | --- | --- | -5 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =-1A, T _J =25°C | --- | --- | -1.2 | V |
| t _{rr} | Reverse Recovery Time | I _F =-5A, di/dt=-100A/μs, | --- | 38.7 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | T _J =25°C | --- | 22.4 | --- | nC |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=-25V, V_{GS}=-10V, L=0.88mH, I_{AS}=-18.9A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

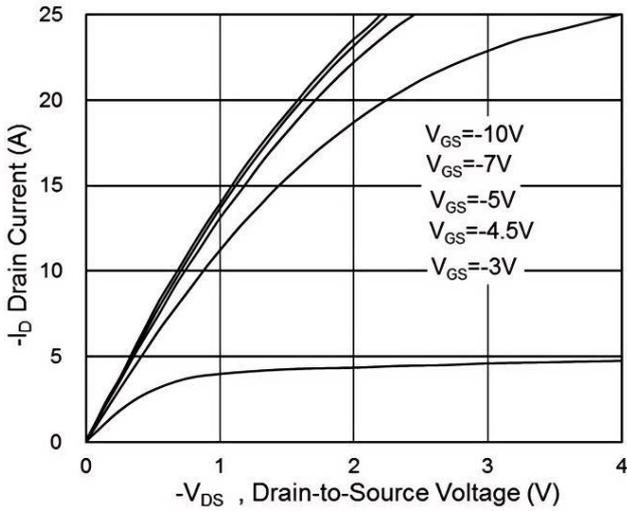


Fig.1 Typical Output Characteristics

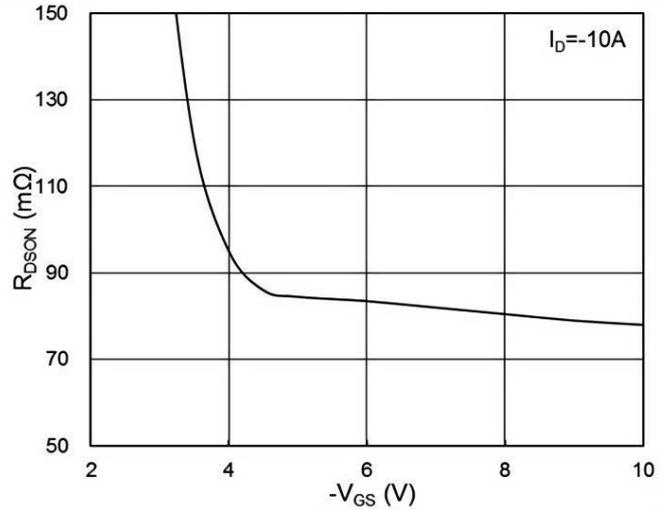


Fig.2 On-Resistance vs. G-S Voltage

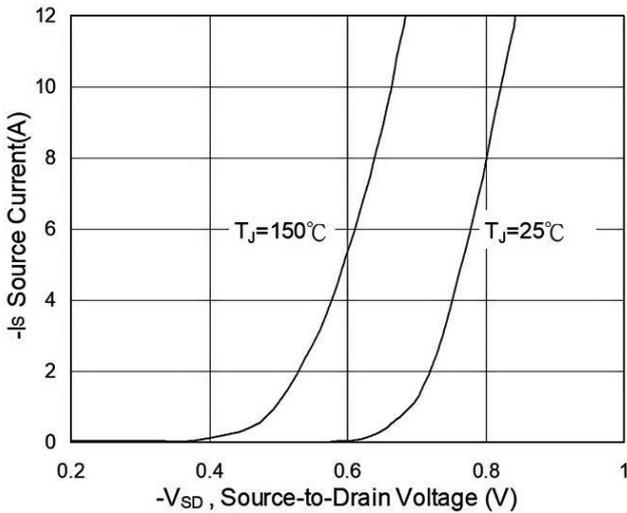


Fig.3 Typical S-D Diode Forward Voltage

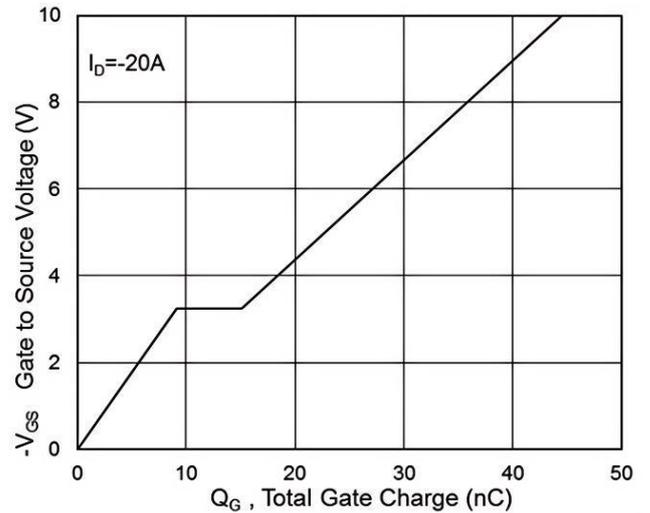


Fig.4 Gate-Charge Characteristics

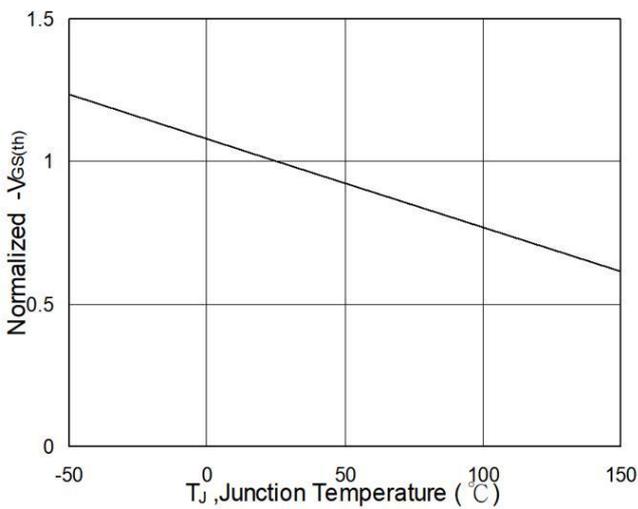


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

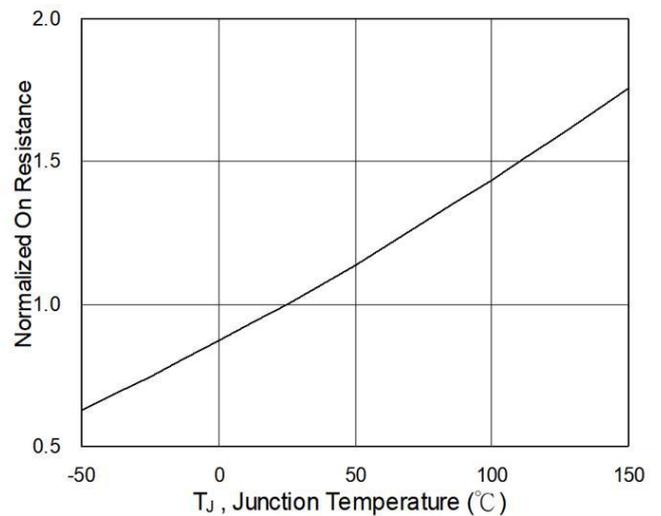


Fig.6 Normalized $R_{DS(on)}$ vs. T_J



P-Ch 100V Fast Switching MOSFETs

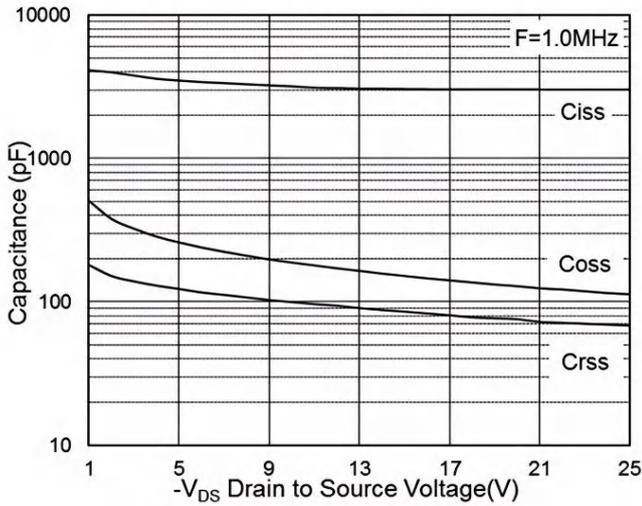


Fig.7 Capacitance

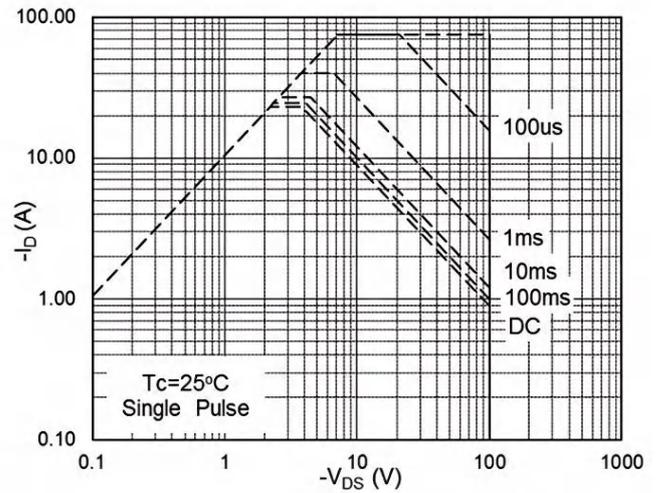


Fig.8 Safe Operating Area

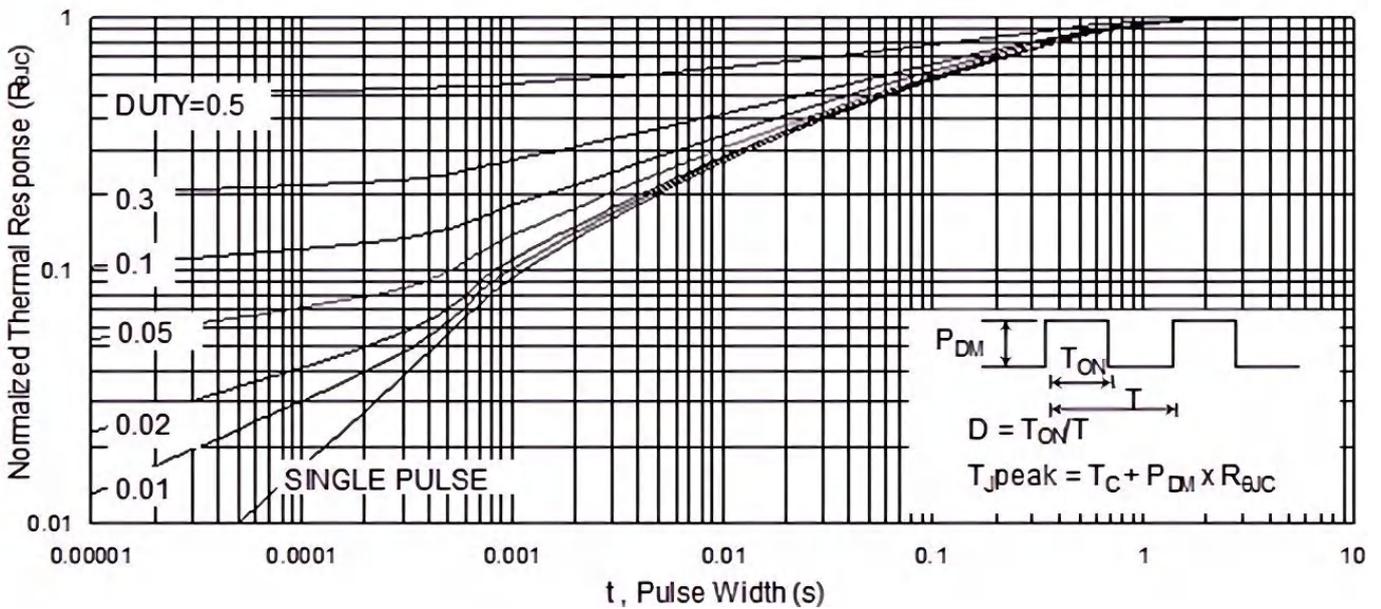


Fig.9 Normalized Maximum Transient Thermal Impedance

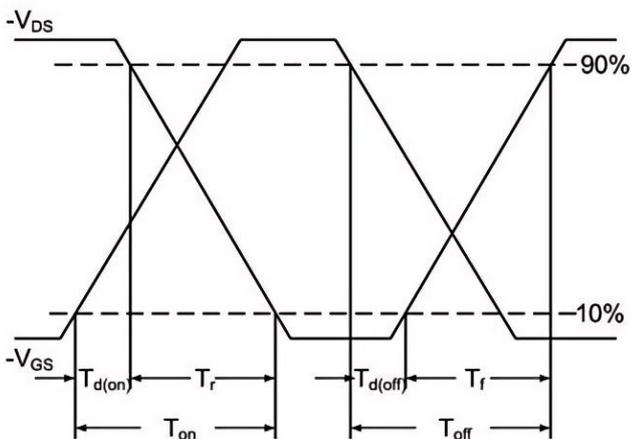


Fig.10 Switching Time Waveform

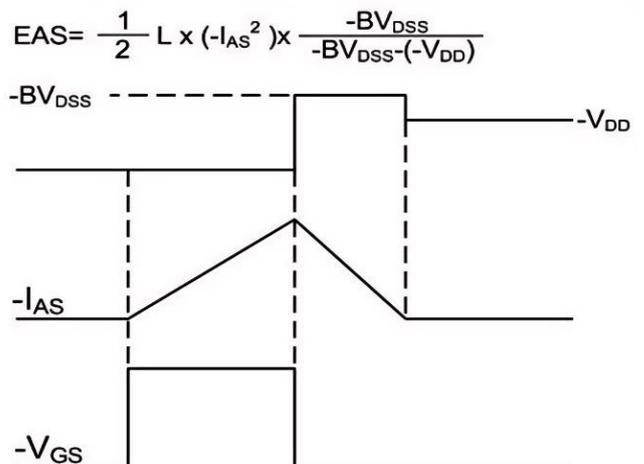
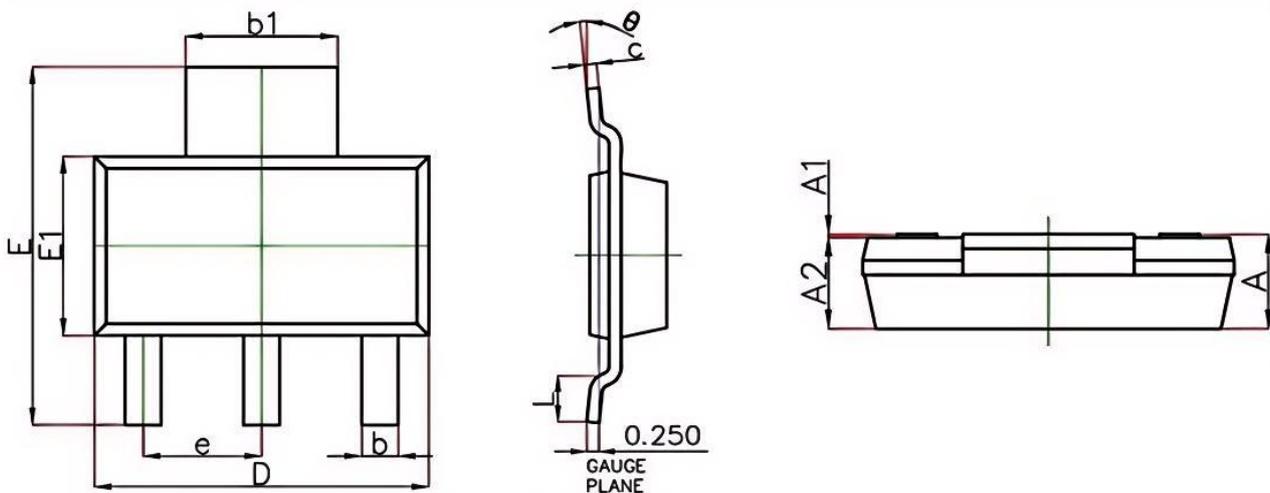


Fig.11 Unclamped Inductive Waveform

Ordering Information

| Part Number | Package code | Packaging |
|-------------|--------------|----------------|
| HSL0115 | SOT-223 | 3000/Tape&Reel |

SOT-223 Package Outline



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|----------|---------------------------|-------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | - | 1.800 | - | 0.071 |
| A1 | 0.020 | 0.100 | 0.001 | 0.004 |
| A2 | 1.450 | 1.750 | 0.057 | 0.069 |
| b | 0.660 | 0.840 | 0.026 | 0.033 |
| b1 | 2.900 | 3.100 | 0.114 | 0.122 |
| C | 0.230 | 0.350 | 0.009 | 0.014 |
| D | 6.300 | 6.700 | 0.248 | 0.264 |
| E | 6.700 | 7.300 | 0.264 | 0.287 |
| E1 | 3.300 | 3.700 | 0.130 | 0.146 |
| e | 2.300(BSC) | | 0.091(BSC) | |
| L | 0.750 | - | 0.030 | - |
| θ | 0° | 10° | 0° | 10° |



HSL0115 Marking:

